

ABSTRACT

The present invention relates to a polishing method and a polishing apparatus for polishing a substrate, such as a wafer, while pressing the substrate against a polishing surface of a polishing pad, and more particularly to a polishing method and a polishing
5 apparatus for polishing a substrate while regulating a polishing load based on measurement values of a film-thickness measuring device. The polishing method includes: controlling a temperature of a polishing surface (3a) of a polishing pad (3) to a predetermined temperature by use of a pad-temperature regulating apparatus (5); and polishing a substrate (W) while controlling a polishing load for pressing the substrate (W)
10 against the polishing surface (3a) based on measurement values from a film-thickness measuring device (7) provided in the polishing pad (3).

Figure 1